HOT-MELT UNDERFILL COMPOSITION
AND METHOD OF APPLICATION

ABSTRACT

[0082] This invention provides a process for applying a wafer level underfill comprising: providing a solvent-free hot-melt underfill composition; melting the underfill; applying the underfill in a uniform layer to the active side of a semiconductor wafer; returning the underfill to a solid state; optionally B-staging the underfill; optionally removing any excess underfill from the bumps on the wafer; and dicing the wafer into individual dies.

(Figure 2a)